IN THE CLAIMS:

Please cancel claims 40 and 46-54 without prejudice, add new claims 55-60, and amend the claims as follows:

1-33 (Canceled)

34. (Currently Amended) A method for removing a metal layer from a substrate, comprising:

rotating a substrate in a face up position on a rotatable substrate support member;

positioning a cathode fluid dispensing nozzle over ~~a central portion of~~ the substrate;

dispensing a metal removing solution from the cathode fluid dispensing nozzle onto the ~~central portion of the~~ substrate; ~~and~~

applying an electrical bias between the substrate and the cathode fluid dispensing nozzle; and

pivoting the cathode fluid dispensing nozzle in order to dispense the metal removing solution across a surface of the substrate while the substrate is rotating.

35. (Currently Amended) The method of claim 34, further comprising adjusting a radial position of the cathode fluid dispensing nozzle ~~outward from the central portion of the substrate~~ in response to a parameter [[r]] of the electrical bias exceeding a predetermined threshold.

36. (Original) The method of claim 34, wherein applying the electrical bias further comprises electrically connecting a negative output of a power supply to the cathode fluid dispensing nozzle and electrically connecting a positive output of the power supply to the substrate.

37. (Original) The method of claim 36, wherein connecting the positive output of the power supply to the substrate comprises electrically contacting a backside conductive layer on the substrate with an anode contact ring positioned on the substrate support member.

38. (Original) The method of claim 37, wherein electrically contacting the backside conductive layer further comprises electrically engaging the backside conductive layer with a plurality of radially positioned conductive electrical contacts formed into the anode contact ring.

39. (Previously Presented) The method of claim 38, wherein each of the plurality of radially positioned conductive electrical contacts are in electrical communication with the positive output of the power supply.

40. (Canceled)

41. (Previously Presented) The method of claim 35, wherein adjusting the radial position of the cathode fluid dispensing nozzle outward comprises:

removing the metal layer from a first annular area on the surface of the substrate, wherein the first annular area corresponds to the area covered by the cathode fluid dispensing nozzle during a rotation of the substrate; and

adjusting the radial position of the nozzle outward to a second annular area on the surface of the substrate, wherein the second annular area immediately circumscribes the first annular area and has the metal layer remaining thereon.

42. (Original) The method of claim 34, further comprising depositing a backside conductive layer on a bevel portion of the substrate extending onto a portion of a backside of the substrate

43. (Original) The method of claim 34, further comprising vacuum chucking the substrate to the rotatable substrate support member and electrically contacting the substrate.

44. (Previously Presented) The method of claim 34, wherein applying an electrical bias comprises electrically engaging the substrate with a contact ring.

45. (Original) The method of claim 44, wherein the contact ring electrically engages a production surface of the substrate proximate a perimeter thereof.

46-54. (Canceled)

55. (New) The method of claim 34, further comprising dispensing a neutralizing fluid onto the substrate surface to dilute the metal removing solution.

56. (New) The method of claim 55, wherein the neutralizing fluid is dispensed by a dilution nozzle.

57. (New) The method of claim 55, wherein the neutralizing fluid and the metal removing solution are dispensed on separate positions of the substrate surface.

58. (New) The method of claim 34, wherein the cathode fluid dispensing nozzle is pivoted when at least one of a plating circuit voltage and a plating circuit resistance exceeds a predetermined threshold.

59. (New) A method for removing a metal layer from a substrate, comprising:

rotating a substrate in a face up position on a rotatable substrate support member;

positioning a cathode fluid dispensing nozzle over a central portion of the substrate;

dispensing a metal removing solution from the cathode fluid dispensing nozzle onto the central portion of the substrate;

applying an electrical bias between the substrate and the cathode fluid dispensing nozzle;

pivoting the cathode fluid dispensing nozzle in order to dispense the metal removing solution across a surface of the substrate while the substrate is rotating; and

removing a conductive layer from the backside of the substrate.

60. (New) The method of claim 59, wherein the cathode fluid dispensing nozzle is pivoted when at least one of a plating circuit voltage and a plating circuit resistance exceeds a predetermined threshold.